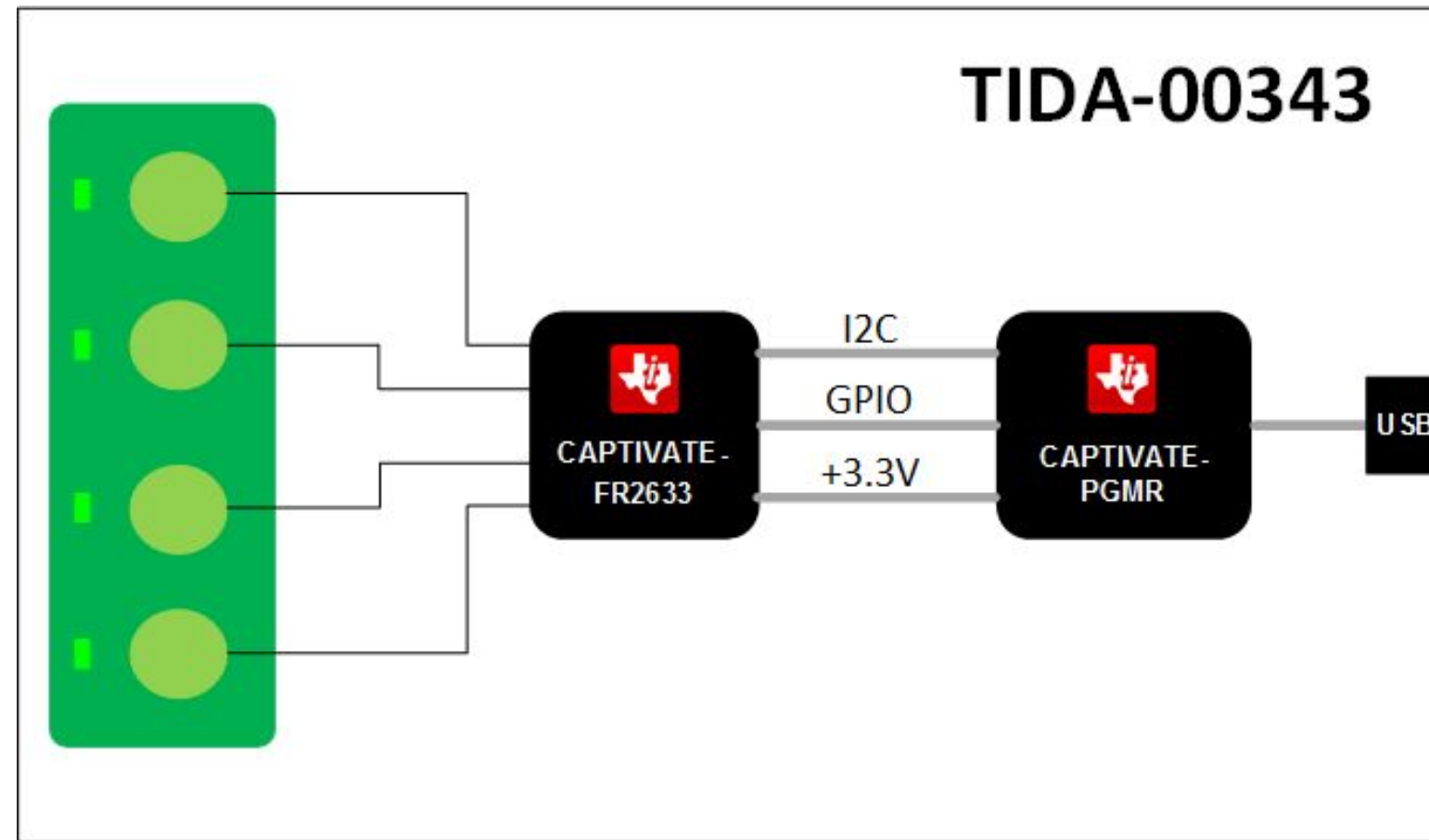


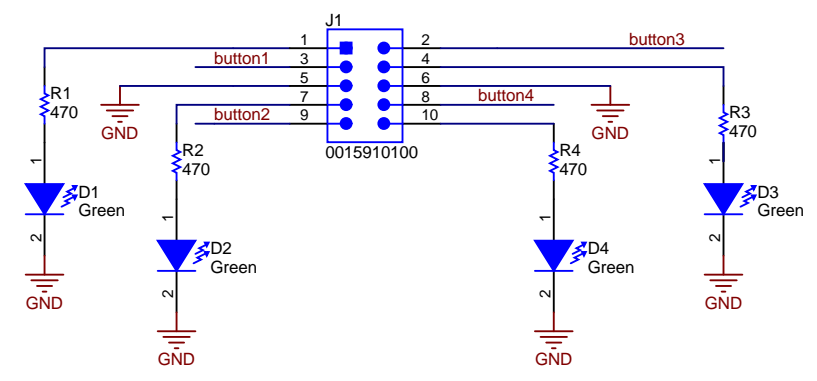
Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A




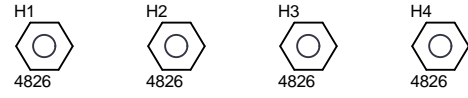
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TID #: TIDA-00343	Project Title: Low Power Touch Through Glass		
Number: TIDA-00343	Rev: E1	Sheet Title: Block Diagram TIDA-00343	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3	
Drawn By:	File: TIDA-00343_CoverSheet_SchDoc	Size: B	
Engineer: Giovanni Campanella	Contact: http://www.ti.com/support		



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TID #: TIDA-00343	Project Title: Low Power Touch Through Glass		
Number: TIDA-00343	Rev: E1	Sheet Title: Schematic Electrodes Board	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3	
Drawn By: Giovanni Campanella	File: TIDA-00343_Schematic.SchDoc	Size: B	
Engineer: Giovanni Campanella	Contact: http://www.ti.com/support		



PCB Number: TIDA-00343
PCB Rev: E1

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Pb-Free Symbol

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Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: TIDA-00343	Project Title: Low Power Touch Through Glass	Sheet: 3 of 3	
Number: TIDA-00343	Rev: E1	Sheet Title: HW Electrodes Board	© Texas Instruments 2016
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By: Giovanni Campanella	File: TIDA-00343_Hardware.SchDoc	Contact: http://www.ti.com/support	

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